ABS09

Request Samples (>)



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4.1 x 1.5 x 0.9 mm RoHS/RoHS II Compliant MSL Level = N/A

Features

- Low frequency in small size SMD
- 0.9mm height ideal for high density circuit boards
- Ceramic package offers excellent environmental & heat resistance
- -40°C to +85°C for industrial applications

Applications

- Wide range in communication & measuring equipment
- Commercial & Industrial applications
- Wireless communications

Key Electrical Specifications

Parameter	Specification
Nominal frequency:	32.768 kHz
Operating temperature:	- 40° C to + 85°C
Turn-over temperature:	+25° C ± 5° C
Storage temperature:	- 55° C to + 125°C
Frequency tolerance:	\pm 20 ppm max.
Temperature coefficient:	- 0.034±0.006 ppm/T ²
Equivalent series resistance:	70 kohms max.
Load capacitance CL:	12.5 pF (see options)
Drive level:	1.0 μW max.
Aging @ 25° C first year:	\pm 5 ppm max.
Insulation resistance:	500Mohms with 100 Vdc ± 15 V
Shunt capacitance C0:	1.0pF typ.
Motional capacitance C1:	2.0fF typ.



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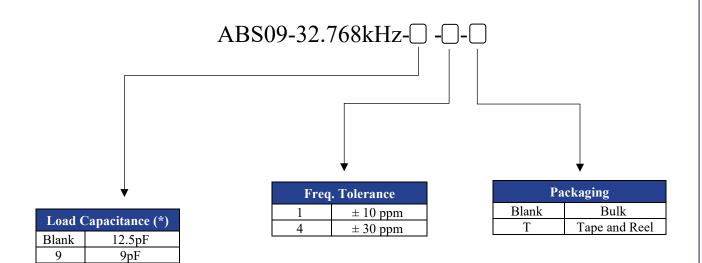


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4.1 x 1.5 x 0.9 mm **RoHS/RoHS II Compliant** MSL Level = N/A

OPTIONS AND PART IDENTIFICATION (Left blank if standard)



(*) Contact ABRACON for non-standard load capacitance

7pF

7



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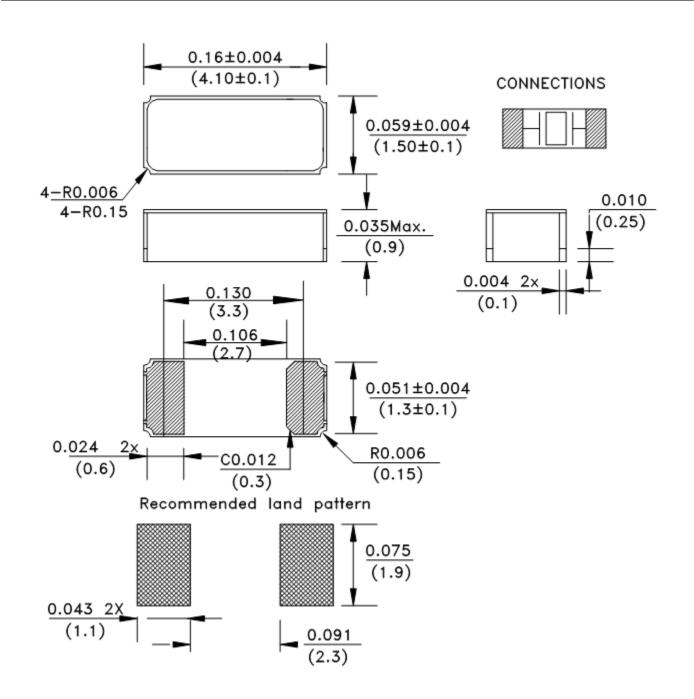


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4.1 x 1.5 x 0.9 mm RoHS/RoHS II Compliant MSL Level = N/A

MECHANICAL DIMENSIONS



Dimensions: inches (mm)



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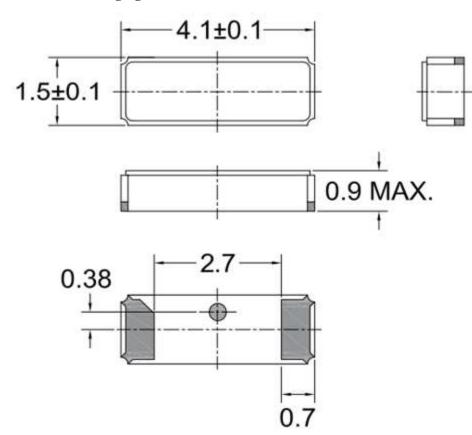


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Alternative Packaging 1:



Dimensions: mm



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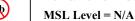
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4.1 x 1.5 x 0.9 mm **RoHS/RoHS II Compliant**



Reflow Profile [JEDEC J-STD-020]

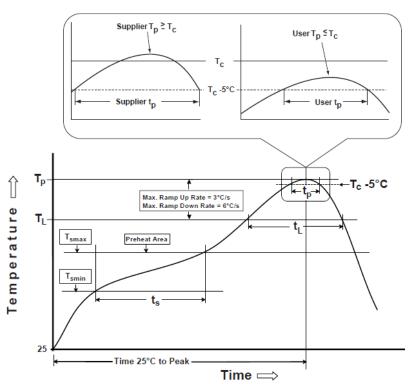


Table 1 **SnPb Eutectic Process**

Classification Temperatures (T _c)				
Package Thickness	Volume mm³ <350	Volume mm³ <u>></u> 350		
<2.5 mm	235 °C	220 °C		
>2.5 mm	220 °C	220 °C		

Table 2

Pb-Free Process Classification Temperatures (T _c)						
Package Thickness	Volume mm³ <350	Volume mm ³ 350-2000	Volume mm³ >2000			
<1.6 mm	260 °C	260 °C	260 °C			
1.6 mm - 2.5 mm	260 °C	250 °C	245 °C			
. 2 5	250 %	245 %	245 %			

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat / soak		
Temperature minimum (T _{smin})	100°C	150°C
Temperature maximum (T _{smax})	150°C	200°C
Time (T _{smin} to T _{smax}) (t _s)	60 - 120 sec.	60 - 120 sec.
Average ramp-up rate (T _{smax} to T _P)	3°C/sec. max	3°C/sec. max
Liquidous temperature (T _L)	183°C	217°C
Time at liquidous (t _L)	60 - 150 sec.	60 - 150 sec.
Peak package body temperature (T _P)*	see Table 1	see Table 2
Time (t _p)** within 5°C of the specified classification temperature (T _C)	20 sec.	30 sec.
Ramp-down rate (T _p to T _{smax})	6°C/sec. max	6°C/sec. max
Time 25°C to peak temperature	6 min. max	8 min. max
Reflow cycles	2 max	2 max

^{*}Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.



^{**}Tolerance for time at peak profile temperature (t_p) is defined as supplier minimum and a user maximum.

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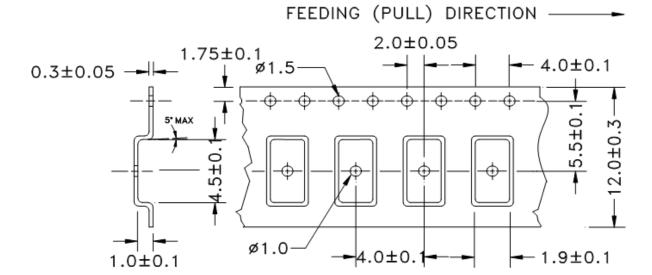


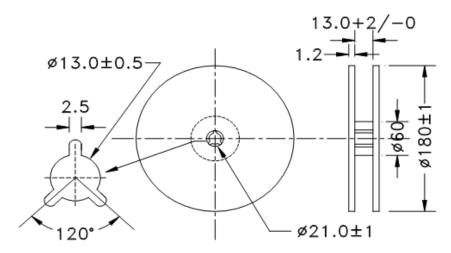
4.1 x 1.5 x 0.9 mm **RoHS/RoHS II Compliant** MSL Level = N/A



PACKAGING

T= tape and reel (3,000pcs/reel)





Dimension: mm

ATTENTION: Abracon LLC's products are COTS - Commercial-Off-The-Shelf products; suitable for Commercial, Industrial and, where designated, Automotive Applications. Abracon's products are not specifically designed for Military, Aviation, Aerospace, Life-dependent Medical applications or any application requiring high reliability where component failure could result in loss of life and/or property. For applications requiring high reliability and/or presenting an extreme operating environment, written consent and authorization from Abracon LLC is required. Please contact Abracon LLC for more information.

